



<b>Title of Change:</b>	Copper wire conversion and mold compound change for LA6242H.			
<b>Proposed first ship date:</b>	1 April 2016			
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < Tsutomu Shimazaki@ onsemi.com > < Takashi.Harashima@onsemi.com>< Takeshi2.Hoshino @onsemi.com>< Kazumi. Onda@onsemi.com> < Shinya Okada@onsemi.com>< Yoshiyuki Nunokawa@onsemi.com>			
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or < jun.hasunuma@onsemi.com>			
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < Satoru.Fujinuma@onsemi.com>			
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.			
<b>Change Part Identification:</b>	Affected products will be identified with date code.			
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____			
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____			
<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Tarlac City, Philippines <input type="checkbox"/> External Foundry/Subcon site(s)			
<b>Description and Purpose:</b>				
This is a Final Process Change Notification for below contents.				
1) Gold wire connecting chip and Lead will be changed to Copper wire. 2) Mold resin will be changed to suitable for Copper wire. 3) LA6242H-TE-L-E:Change from MSL1 to MSL3(packaging will change from S-15 to S-16)				
There is no change of the electrical characteristic specifications with this changing.				
<b>Reliability Data Summary:</b>				
QV DEVICE NAME : LA6242H				
PACKAGE :HSOP28HC				
Test	Specification	Condition	Interval	Results
HTOL	EIAJ ED-4701/100	Tj=Tjmax, Vcc=Operatingmax	1000 hrs	0/22
THB*	EIAJ ED-4701/100	85°C, 85% RH, Vcc=recommended	1000 hrs	0/22
TC*	EIAJ ED-4701/100	Ta= -65°C to +150°C	100 cyc	0/22
AC*	EIAJ ED-4701-3	Ta=121°C ,RH=100% ,205kPa	50 hrs	0/22
HTSL	EIAJ ED-4701/200	Ta= 150°C	1000 hrs	0/22
RSH	EIAJ ED-4701/300	Ta = 255°C , 10 sec (peak 260°C)	2times	0/22
Notes: The test items with * mark are put into operation after the reflow soldering (at 255°C for 10seconds)				

**Electrical Characteristic Summary:**

There is no change in the electrical performance. Datasheet specifications remain unchanged.

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
LA6242H-CL-TLM-E	LA6242H
LA6242H-TE-L-E	LA6242H
LA6242H-TRM-E	LA6242H